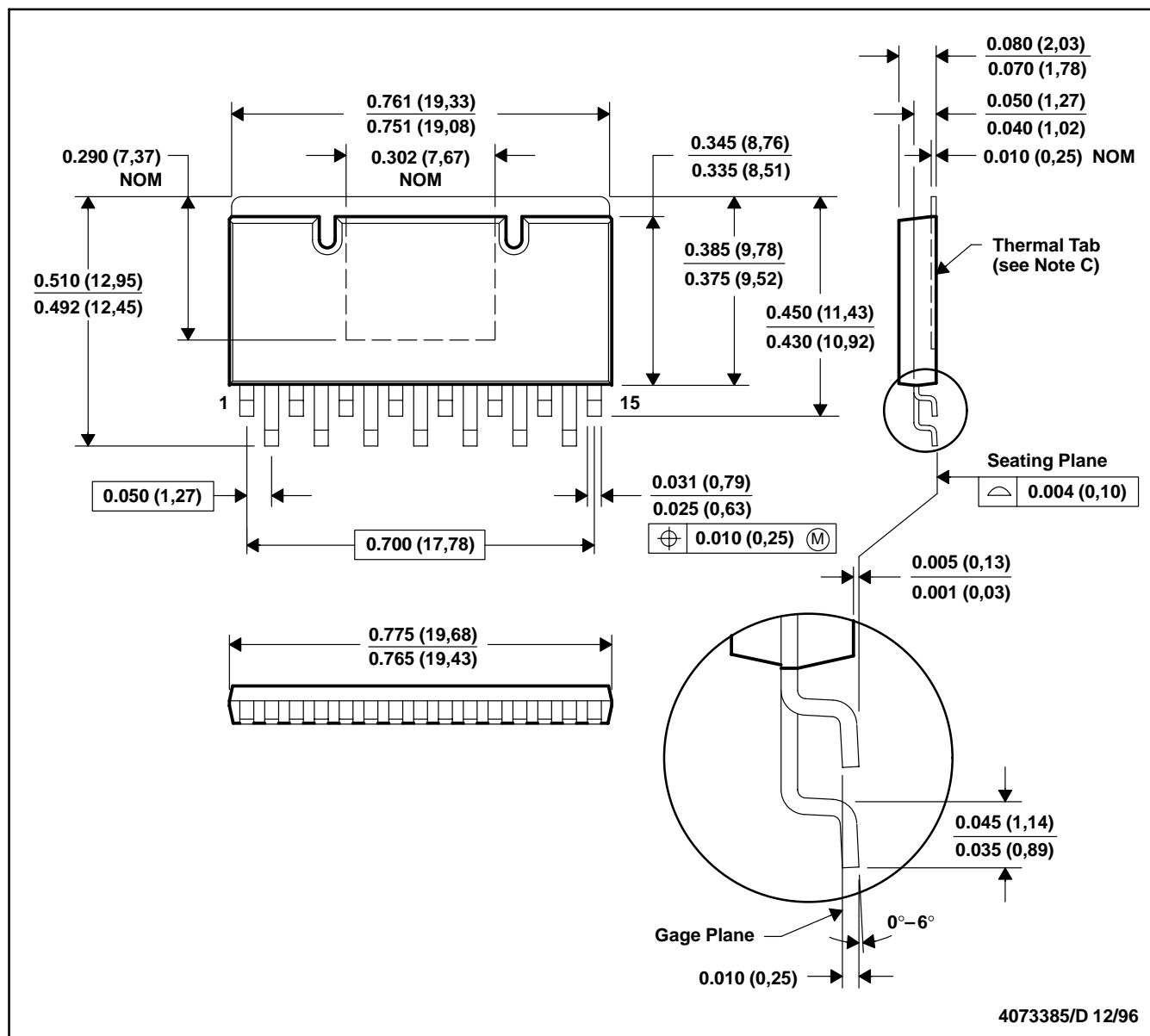


## KTC (R-PSFM-G15)

## PowerFLEX™ PLASTIC FLANGE-MOUNT PACKAGE



- NOTES:
- All linear dimensions are in inches (millimeters).
  - This drawing is subject to change without notice.
  - The heatsink area is approximately 78K sq mils.
  - Dimensions do not include mold protrusions, not to exceed 0.006 (0,15).

PowerFLEX is a trademark of Texas Instruments Incorporated.



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